

REWORKABLE EDGEBOND ADHESIVE

UA-2605-B is a reworkable edgebond adhesive for BGA's, CSP's, and other surface mount components. The adhesive enhances thermal cycle performance as well as resistance against shock and vibration. The adhesive cures quickly at low temperature and exhibits excellent adhesion to organic substrates.

TYPICAL PROPERTIES

Color	Black
Filler Content, %	50
Viscosity, 25°C	
SSA #14, 1 rpm, cps	220,000
Cure Conditions, minutes	
130°C	10
140°C	5
150°C	1
Specific Gravity (g/cc)	1.56
Shelf Life @ -5°C, months	12
Pot Life @ 25°C, days	14

CURED PROPERTIES

CTE1, ppm/°C	30
CTE2, ppm/°C	104
Tg, °C (TMA)	134
Storage Modulus, GPa (DMA)	7.8
Dielectric Constant (Dk), 10GHz	3.3
Dissipation Factor (Df), 10GHz	0.022
Tensile Strength, kpsi	11.6
Elongation, %	2.0
Young's Modulus, GPa	6.5
Volatiles Content, wt% loss on cure	<2.0

DIRECTIONS FOR USE

Dispense adhesive along the perimeter of the assembled component. Leave a small edge section unbonded so as not to completely seal the air under the chip. This is to ensure that there is an outlet for any expansion of the air during processing. DO NOT LEAVE ANY OF THE CORNERS UNBONDED. Cure according to the listed cure schedules. Recommended cure temperature is actual temperature of the adhesive. For other cure temperatures, consult your Zymet sales representative.

DIRECTIONS FOR REWORK

Heating the exposed adhesive fillet facilitates ease of removal. Use a heat resistant probe (i.e. orange stick) to scrape away the heated adhesive. Heat between 130°C -180°C. Use the lowest practical temperature and minimize the length of time at high temperature prior to removal. For more detailed instructions, contact your Zymet sales representative.

STORAGE AND HANDLING

Store at -5°C, or below. Thaw completely before use. Use good industrial hygiene to avoid skin and eye contact. Wash off affected area with soap and water.

AVAILABILITY

30-cc Syringes, MPN# UA2605B-030 55-cc Syringes, MPN# UA2605B-055 170-cc Cartridges, MPN# UA2605B-170

Refer to SDS before use or disposal.

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